

WHAT IS CLAIMED IS:

1. A substrate having a metallic pattern containing a repaired defect, wherein the repaired defect includes a metal thin-film deposited from a metallic organic compound.
2. A substrate having a metallic pattern containing a repaired defect according to claim 1, wherein said metallic pattern is an electrode.
3. A substrate having a metallic pattern containing a repaired defect according to claim 1, wherein said metallic pattern is an opaque film.
4. A substrate having a metallic pattern containing a repaired defect according to claim 1, wherein said metallic organic compound is gold-resinate-base paste for low temperature baking.
5. A method for repairing a metallic pattern on a substrate, said method comprising steps of:

 applying a metallic organic compound to a defective in a metallic pattern overlying said substrate; and

 heating said organic compound to deposit a metallic thin film in said defective.
6. A method for repairing a metallic pattern on a substrate according to claim 5, wherein energy from a semiconductor laser is used as a heat source for heating said metallic organic compound.

7. A method for repairing a metallic pattern on a substrate according to claim 6, wherein said metallic organic compound is first subjected to a provisionally baking process and second to a main baking process, wherein the output of said semiconductor laser is increased, and wherein the substrate is cooled thereafter.

8. A method for repairing a metallic pattern on a substrate according to claim 5, further comprising a step of removing a protruding portion of a deposited metallic thin film from metallic pattern.

9. A device for repairing a defect in a metallic pattern overlying a substrate, said device comprising:

a receiving part for holding a metallic organic compound thereon;

a transfer body moving between said receiving part and said defective in the metallic pattern and transferring the metallic organic compound held on said receiving part to said defect; and

a semiconductor laser unit for baking said metallic organic compound.

10. A device for repairing a defect in a metallic pattern overlying a substrate according to claim 9, further comprising a laser radiating unit for removing a portion protruding from said metallic pattern, wherein said metallic pattern comprises an opaque film.

11. A device for repairing a defective part in a metallic pattern overlying a substrate according to claim 9, wherein said semiconductor laser unit includes an output adjusting unit.

12. A substrate having a metallic pattern containing a repaired defect according to claim 2, wherein said metallic organic compound is gold-resinate-base paste for low temperature baking

13. A substrate having a metallic pattern containing a repaired defect according to claim 3, wherein said metallic organic compound is gold-resinate-base paste for low temperature baking.

5 14. A method for repairing a metallic pattern on a substrate according to claim 6, further comprising a step of removing a portion of a deposited metallic thin film protruding from said metallic pattern.

6 15. A method for repairing a metallic pattern on a substrate according to claim 7, further comprising a step of removing a portion of a deposited metallic thin film protruding from said metallic pattern.

16. A device for repairing a defective part in a metallic pattern formed on a substrate according to claim 10, wherein said semiconductor laser unit has an output adjusting unit.